



Board Mates:

Standoffs:



(0.635 mm) .025"

MIT SERIES

MIXED TECHNOLOGY HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MIT

Insulator Material: Liquid Crystal Polymer Contact Material: Phosphor Bronze Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Operating Temp Range:
-55 °C to +125 °C
Voltage Rating:

Max Cycles:

RoHS Compliant:

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (019-057) Board Stacking:

For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- 11 mm, 16 mm, 18.75 mm and 22 mm stack height
- 30 μ" (0.76 μm) Gold
- · Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 76, 95, 114 and 133 positions per row

MATED HEIGHT*		
MIS LEAD STYLE	MIT LEAD STYLE	
	-01	-02
-01	(5.00) .197	(8.00) .315

*Processing conditions will affect mated height. See SO Series for board space tolerances

Some lengths, styles and options are non-standard, non-returnable.



